



US00D353817S

United States Patent [19]

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Wada

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[54] **HEADPHONE**

[75] Inventor: **Joh Wada, Tokyo, Japan**

[73] Assignee: **Sony Corporation, Tokyo, Japan**

[**] Term: **14 Years**

[21] Appl. No.: **4,444**

[22] Filed: **Feb. 5, 1993**

[30] **Foreign Application Priority Data**

Aug. 28, 1992 [JP] Japan 4-25511
 [52] U.S. Cl. **D14/205**
 [58] Field of Search D14/205; 381/183, 187,
 381/188; 379/430, 444

[56] **References Cited**

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Primary Examiner—B. J. Bullock
Attorney, Agent, or Firm—Jay H. Maioli

[57] **CLAIM**

The ornamental design for a headphone, as shown and described.

DESCRIPTION

FIG. 1 is a top, front and right-side perspective view of a headphone, showing my new design;
 FIG. 2 is a top, front and right-side perspective view thereof, shown in the folded position;
 FIG. 3 is a reduced front elevational view thereof;
 FIG. 4 is a reduced rear elevational view thereof;
 FIG. 5 is a reduced left side elevational view thereof;
 FIG. 6 is a reduced right side elevational view thereof;
 FIG. 7 is a reduced top plan view thereof; and,
 FIG. 8 is a reduced bottom plan view thereof.

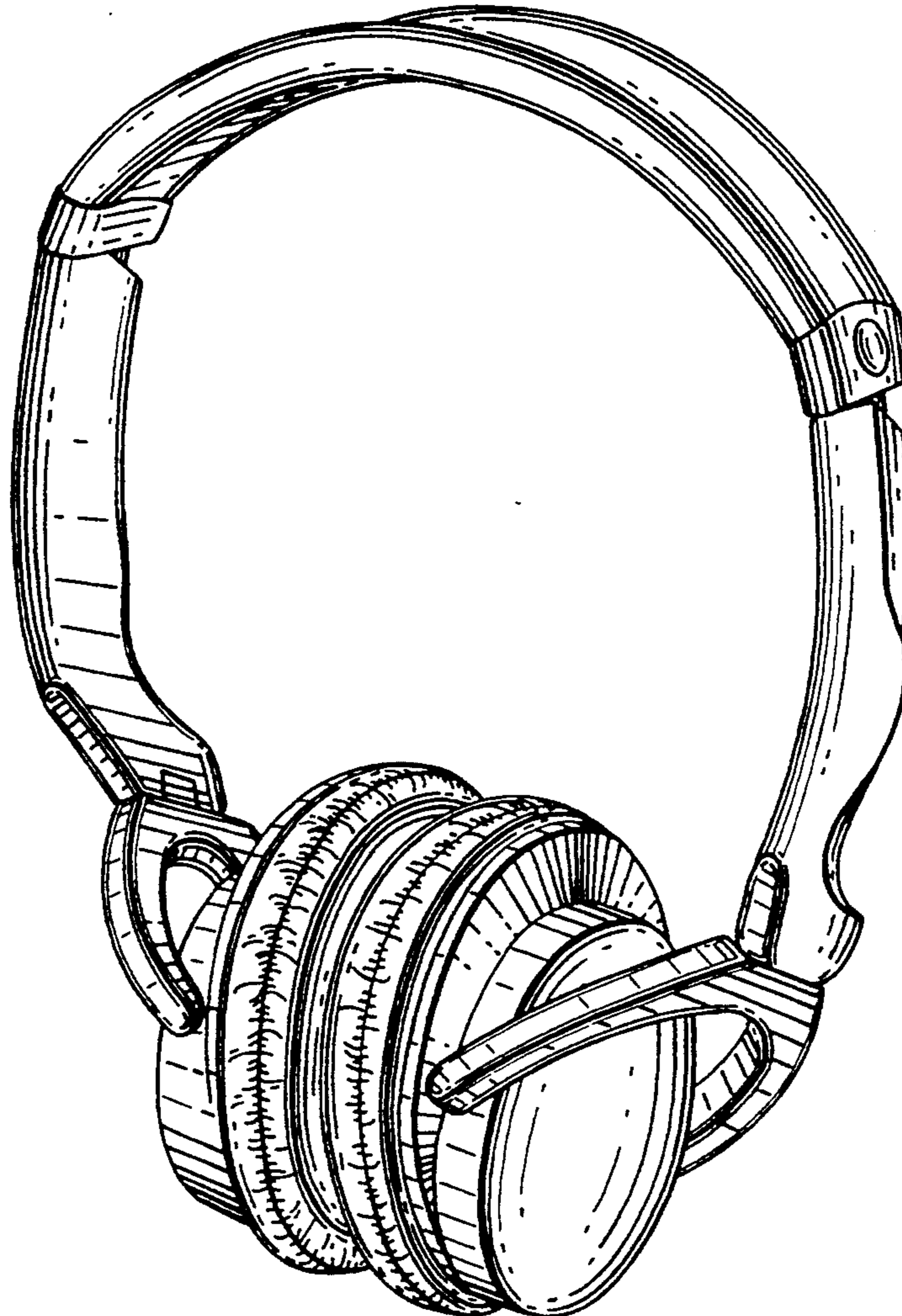


FIG. 1

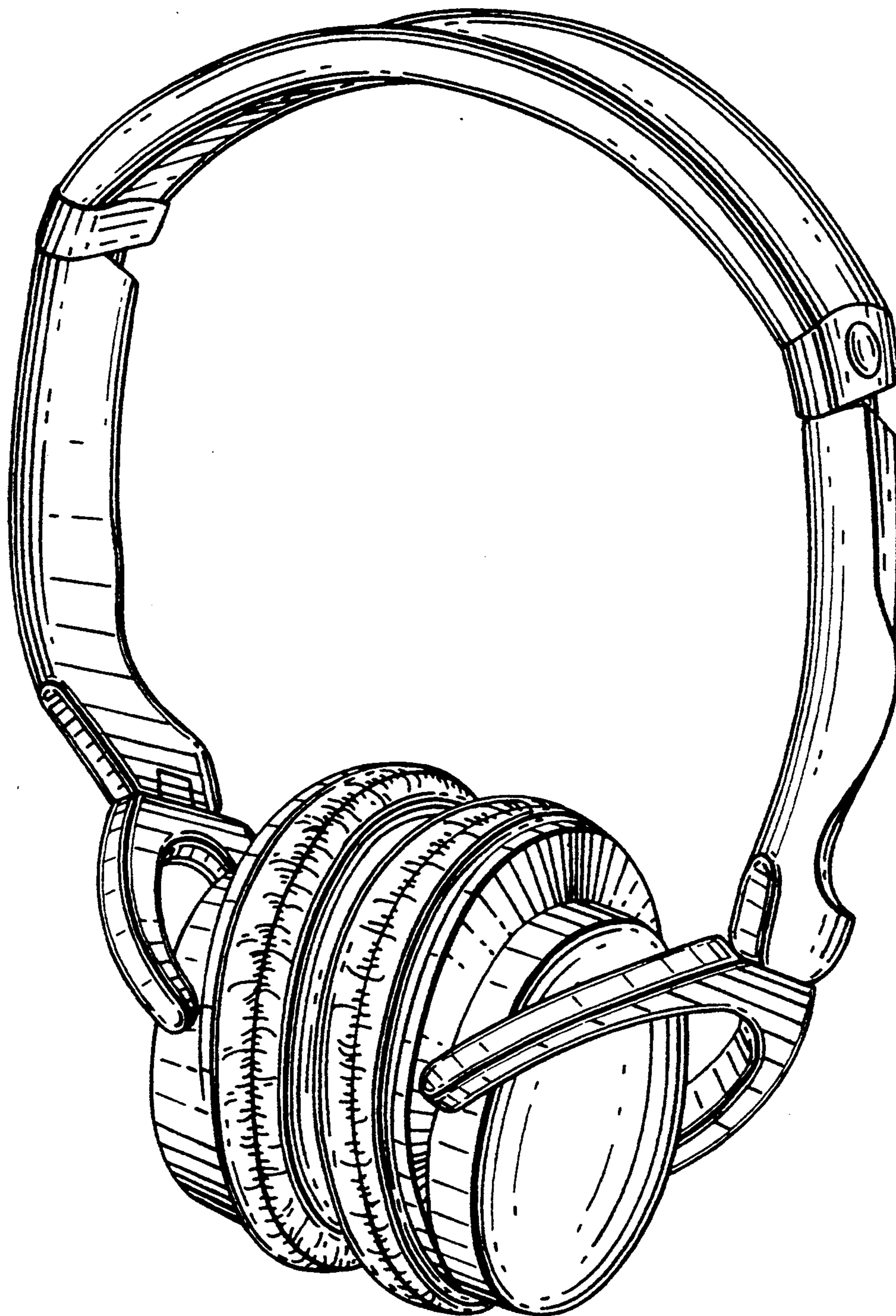


FIG. 2

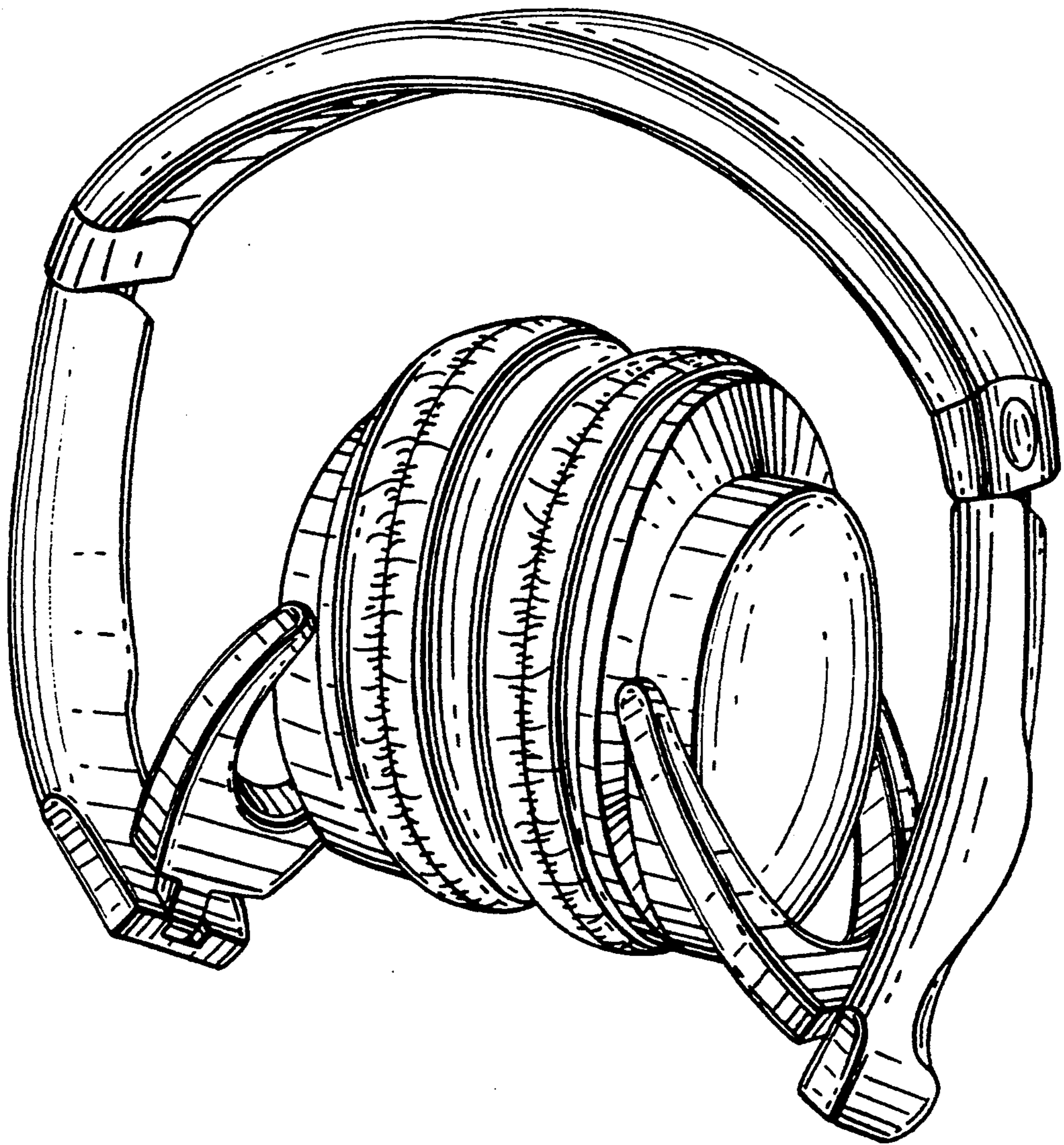


FIG. 3

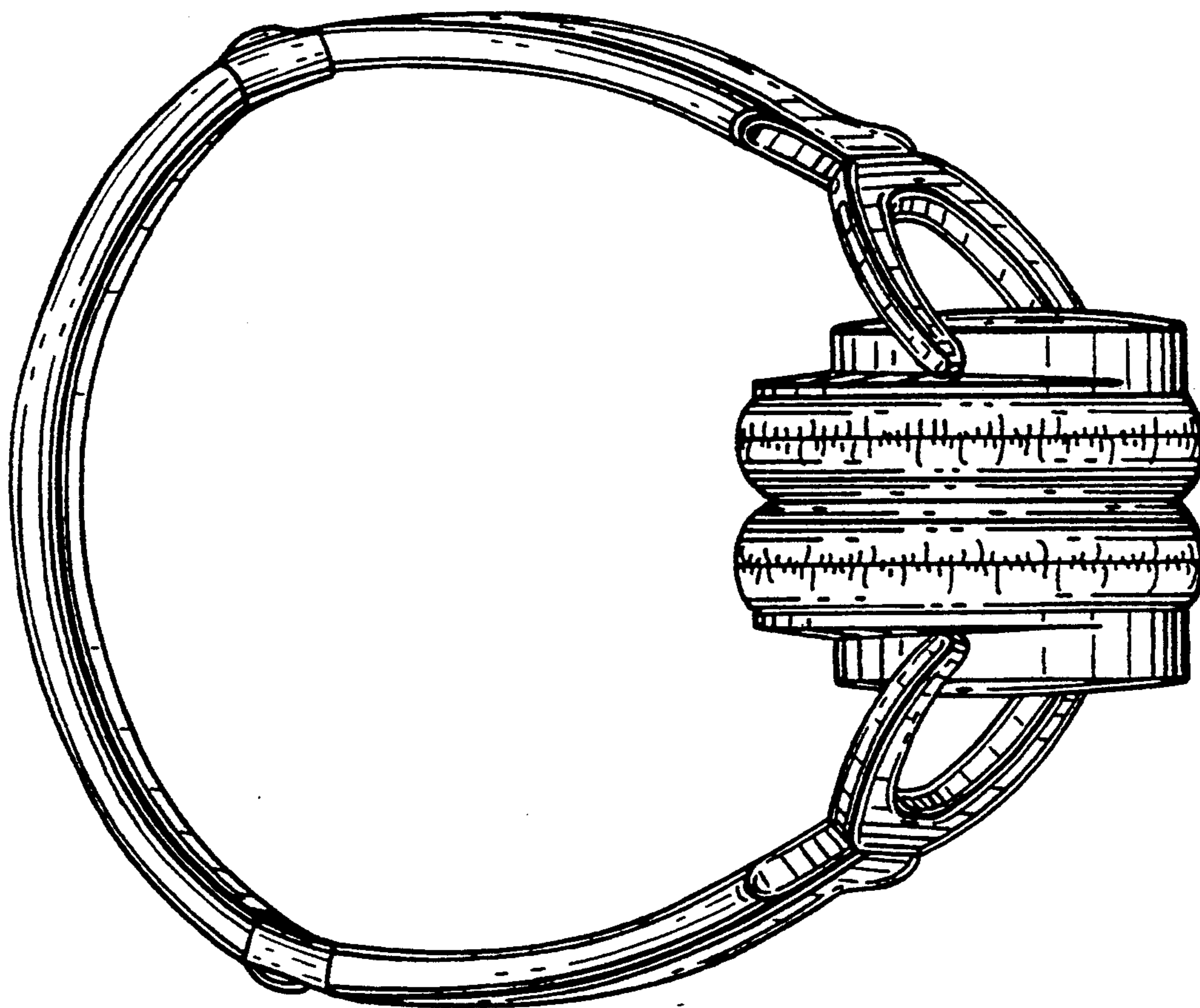


FIG. 5

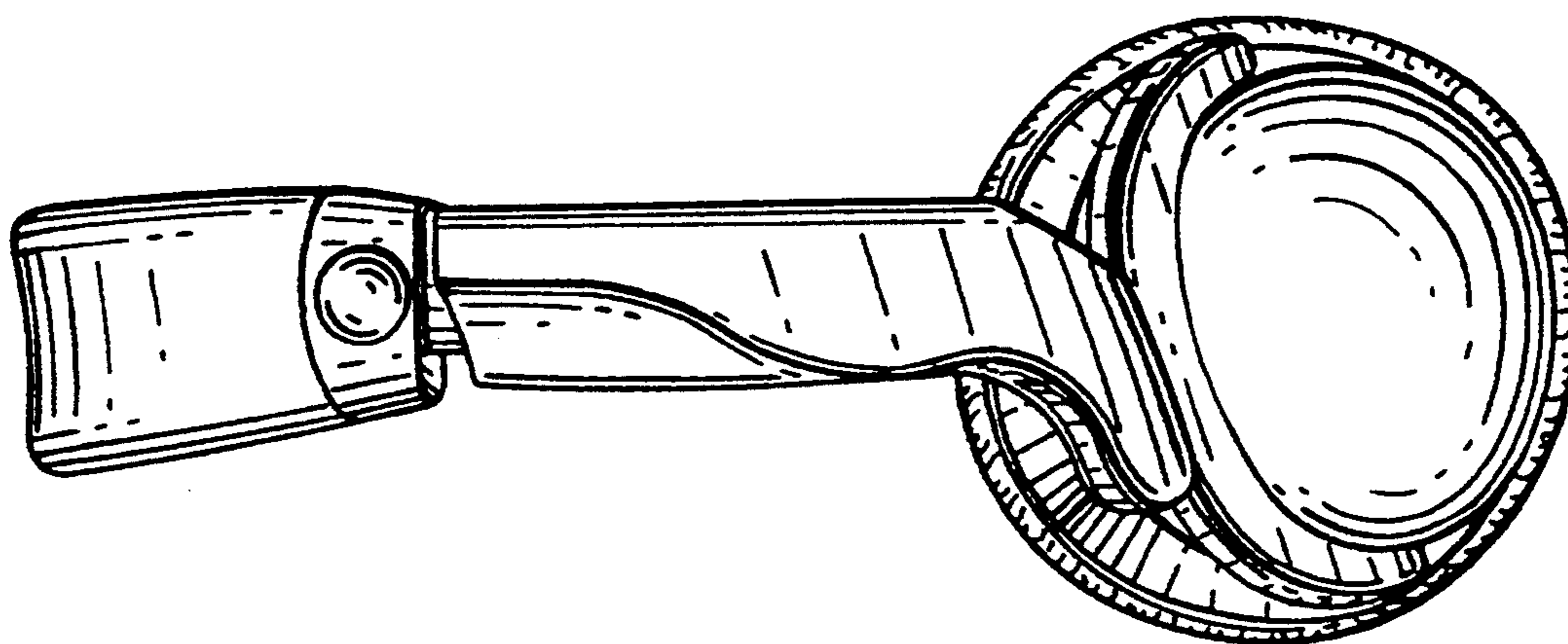


FIG. 4

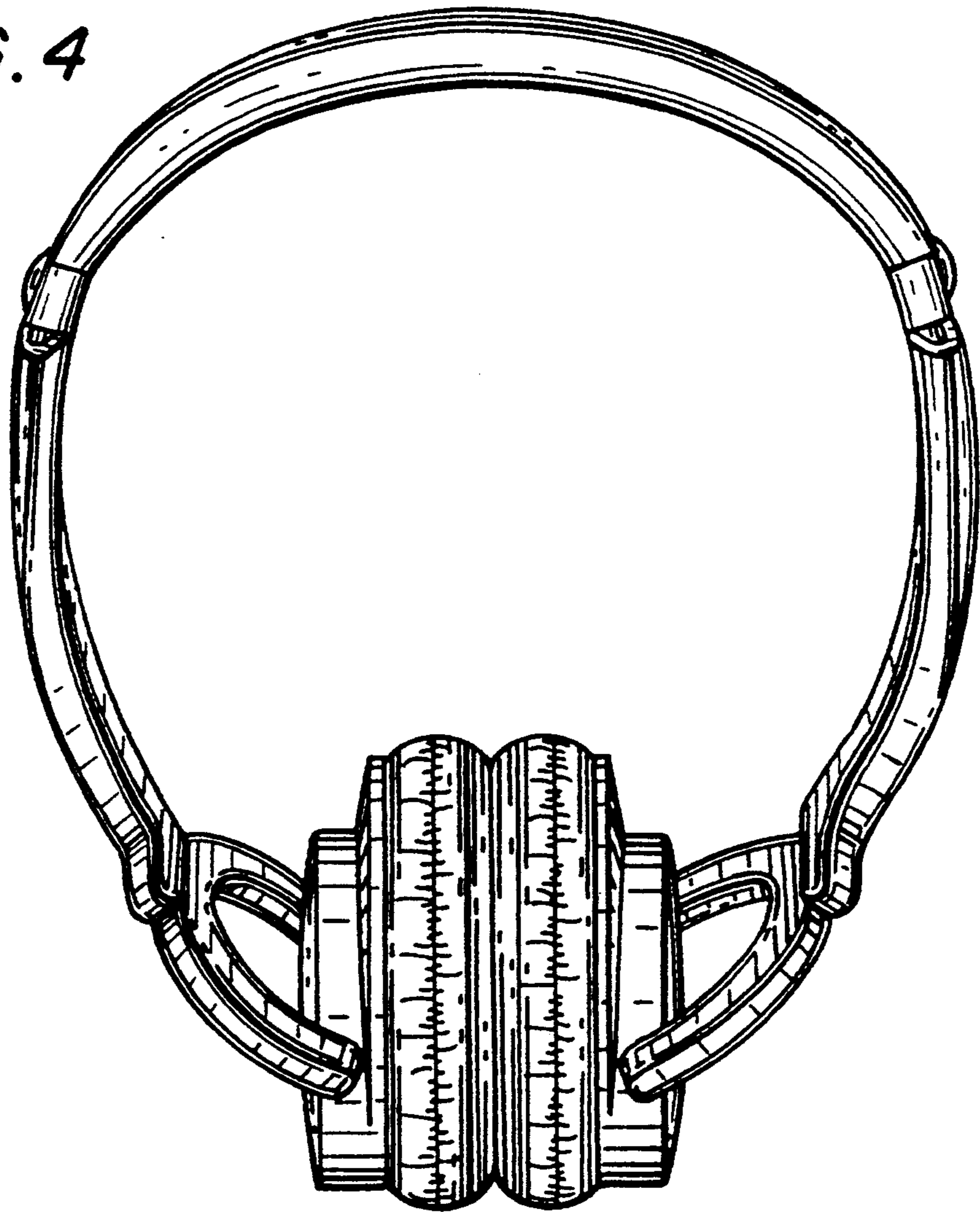


FIG. 8

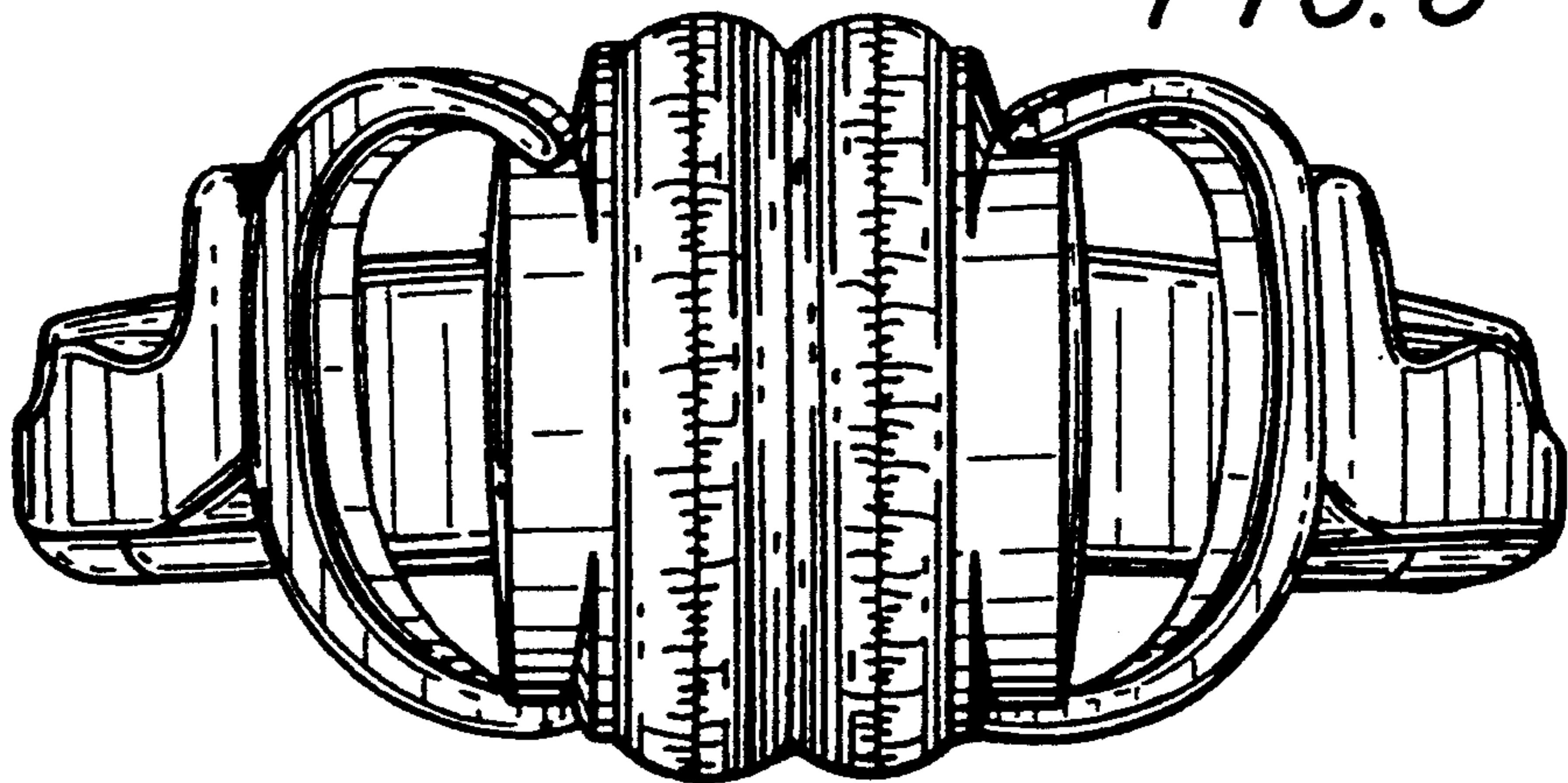


FIG. 6

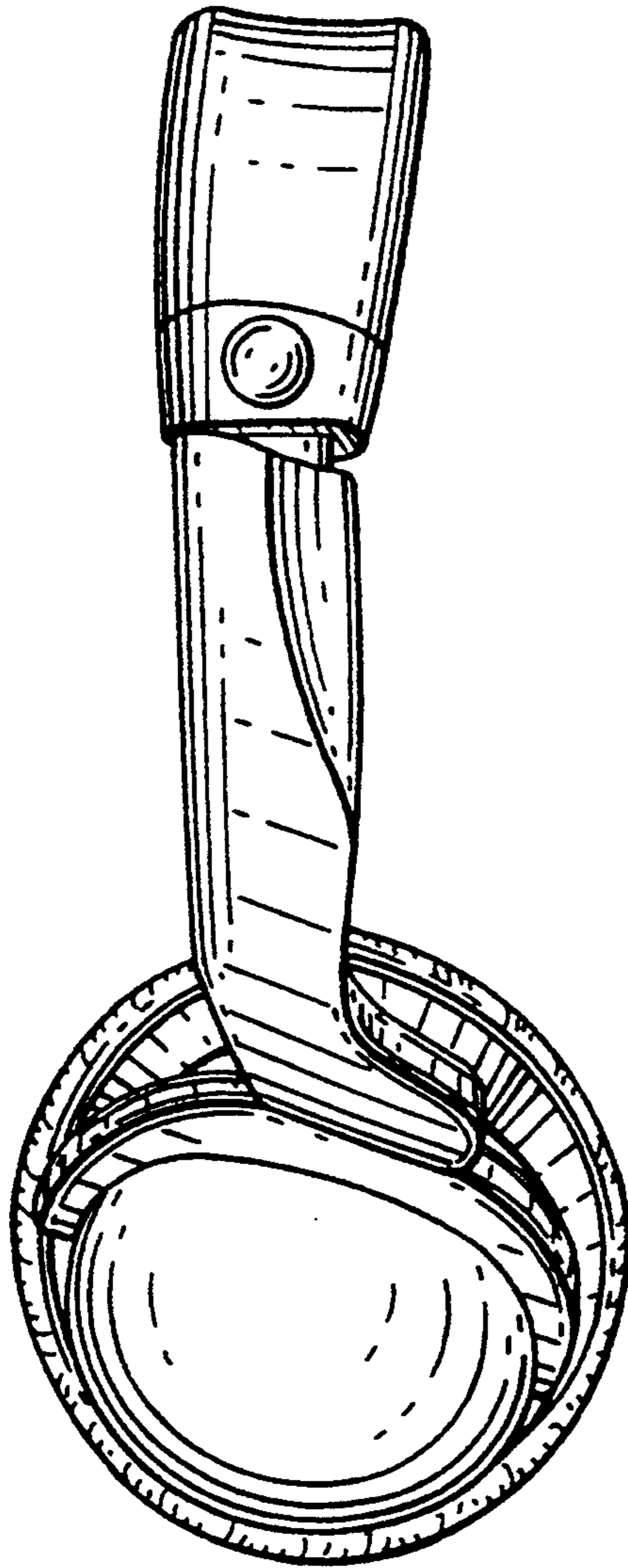


FIG. 7

